SE100PWTG, SE100PWTJ

Vishay General Semiconductor

AUTOMOTIV

ROHS

HALOGEN

FREE

Surface-Mount ESD Capability Rectifier



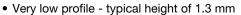
LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS					
I _{F(AV)}	10 A				
V _{RRM}	400 V, 600 V				
I _{FSM}	125 A				
V_F at $I_F = 10 A (T_J = 125 °C)$	0.93 V				
T _J max.	175 °C				
Package	SlimDPAK 2L				
Circuit configurations	Single				

FEATURES

Creepage and clearance distance 2.8 mm minimum



Ideal for automated placement

· Oxide planar chip junction

• Low forward voltage drop

· ESD capability

 Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C

• AEC-Q101 qualified available

- Automotive ordering code: base P/NHM3

 Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

TYPICAL APPLICATIONS

General purpose, power line polarity protection, in both industry and automotive on board charger applications.

MECHANICAL DATA

Case: SlimDPAK 2L

Molding compound meets UL 94 V-0 flammability rating Base P/N-M3 - halogen-free, RoHS-compliant Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

Terminals: matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

3-31D-002 and 3L3D 22-D102

M3 and HM3 suffix meets JESD 201 class 2 whisker test

Polarity: as marked

MAXIMUM RATINGS (T _A = 25 °C unless otherwise noted)						
PARAMETER	SYMBOL	SE100PWTG	SE100PWTJ	UNIT		
Device marking code		SE100PWTG	SE100PWTJ			
Maximum repetitive peak reverse voltage	V_{RRM}	400	600	V		
Maximum average forward rectified current (Fig. 1)	I _{F(AV)} (1)	10		А		
Maximum average forward rectified current (Fig. 1)	I _{F(AV)} (2)	2.7		A		
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I _{FSM}	125		А		
Operating junction and storage temperature range	T _J , T _{STG}	-55 to +175		°C		

Notes

(1) With infinite heatsink

(2) Free air, mounted on recommended copper pad area

SE100PWTG, SE100PWTJ

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ELECTRICAL CHARACTERISTICS (T _J = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
	$I_F = 5.0 \text{ A}$	T 05 °C		0.93	-	
Maximum Instantaneous forward voltage	$I_F = 10.0 \text{ A}$ $T_J = 25 \text{ °C}$	V _E (1)	1.01	1.14] _v	
	$I_F = 5.0 A$	T _J = 125 °C	VF (*/	0.82	-	
	$I_F = 10.0 A$			0.93	1.09	
Reverse current	Rated V _R	T _J = 25 °C	I _R ⁽²⁾	-	20	μА
neverse current	nated V _R	T _J = 125 °C	IR (-)	25	150	
Typical reverse recovery time	$I_F = 0.5 \text{ A}, I_R = 1.0 \text{ A}, I_{rr} = 0.25 \text{ A}$		t _{rr}	2600	-	ns
Typical junction capacitance	4.0 V, 1 MHz		CJ	78	-	pF

Notes

 $^{(1)}\,$ Pulse test: 300 μs pulse width, 1 % duty cycle

(2) Pulse test: pulse width ≤ 40 ms

THERMAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
To recipied the control of the contr	R ₀ JA (1)(2)	75	94	°C/W	
Typical thermal resistance	R _{0JM} (3)	2.2	2.8	C/VV	

Notes

- (1) The heat generated must be less than thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$
- (2) Thermal resistance junction to ambient to follow JEDEC® 51-2A, device mounted on FR4 PCB, 2 oz., standard footprint
- (3) Thermal resistance junction-to-mount to follow JEDEC® 51-14 transient dual interface test method (TDIM)

	IMMUNITY TO ELECTRICAL STATIC DISCHARGE TO THE FOLLOWING STANDARDS (T _A = 25 °C unless otherwise noted)					
ĺ	STANDARD TEST TYPE		TEST CONDITIONS	SYMBOL	CLASS	VALUE
	AEC-Q101-001	Human body model (contact mode)	$C = 100 \text{ pF}, R = 1.5 \text{ k}\Omega$	V _C	НЗВ	> 8 kV

ORDERING INFORMATION (Example)								
PREFERRED P/N	UNIT WEIGHT (g)	NIT WEIGHT (g) PREFERRED PACKAGE CODE		DELIVERY MODE				
SE100PWTJ-M3/I	0.185	I	4500	13" diameter plastic tape and reel				
SE100PWTJHM3/I (1)	0.185	I	4500	13" diameter plastic tape and reel				

Note

(1) AEC-Q101 qualified

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RATINGS AND CHARACTERISTICS CURVES (T_A = 25 °C unless otherwise noted)

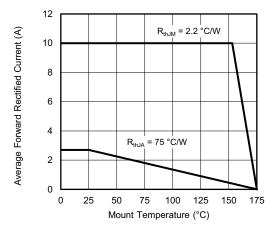


Fig. 1 - Maximum Forward Current Derating Curve

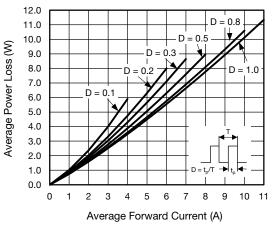


Fig. 2 - Forward Power Loss Characteristics

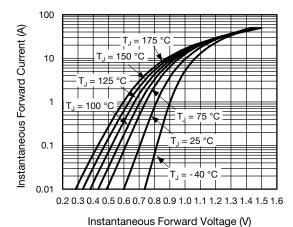


Fig. 3 - Typical Instantaneous Forward Characteristics

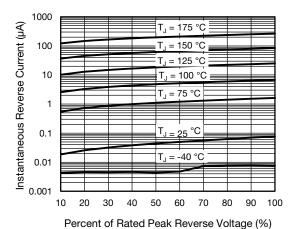


Fig. 4 - Typical Reverse Leakage Characteristics

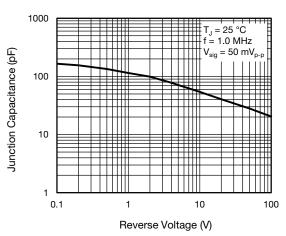


Fig. 5 - Typical Junction Capacitance

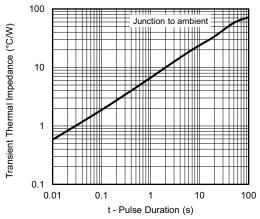
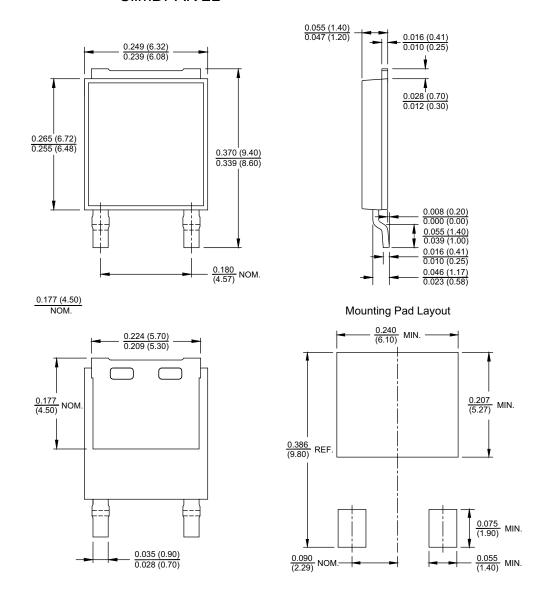


Fig. 6 - Typical Transient Thermal Impedance

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PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

SlimDPAK 2L



Note

· The suggested mounting pad layout is provided for reference only, as actual pad layouts may vary depending on application



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